

Thermal RC network (Foster)

SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base		-	-	0.82	K/W
	Cth ₁	1.128E-04 F		Ą	t:	
	Cth ₂	8.153E-04 F		_ 	tj	
	Cth ₃	6.066E-04 F			┎─┿──┐	
	Cth ₄	2.369E-03 F				1
	Cth ₅	6.973E-03 F		L	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	1
	Cth ₆	1.600E-02 F				
	Cth ₇	5.627E-01 F		r		
	Cth ₈	5.931E+01 F			$\int Rth_2 + Cth_2$	2
	Rth₁	7.791E-04 Ω				
	Rth ₂	1.532E-03 Ω		Г		
	Rth ₃	1.801E-02 Ω			Rth3 🛱 Cth;	3
	Rth ₄	4.374E-02 Ω		L	╧╼	
	Rth₅	1.604E-01 Ω			_	
	Rth ₆	5.174E-01 Ω				
	Rth ₇	9.637E-02 Ω				4
	Rth ₈	3.222E-03 Ω	((P)	└ ─ ╋──┘	
			Ň	$\dot{\checkmark}$	└─ ◆───	
					$\int Rth_5 + Cth_9$	5
						
				Г	└ • ─]	
					Rth6 📥 Cthe	6
				L	∠_ <mark>↓</mark>	
						_
					$\int Rth_7 + Cth_7$	7
					└ ─ ┍─┘	
Part:	BUK7613-100E			г	۲ →	
					Rth8 📥 Cth	8
ate:	11/4/2013				∠	
Nodel Rth	0.84 K/W					
				\downarrow	t _{amb}	
				×	001aal76	8

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